Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-88. (Cancelled)

89. (Previously Presented) A method for removably attaching a planarizing medium to a platen of a planarizing machine, comprising:

applying a signal to the platen that produces an electrostatic attractive force between the platen and the planarizing medium.

- 90. (Original) The method of claim 89, further comprising positioning the platen adjacent to the planarizing medium.
- 91. (Previously Presented) The method of claim 89 wherein the platen includes a conductive plate positioned within the platen, and applying a signal includes providing a signal to the conductive plate positioned within the platen.
- 92. (Previously Presented) The method of claim 89 wherein the planarizing medium includes a polishing pad and a support member and applying a signal includes applying a signal that produces an electrostatic attractive force between the platen and the support member.
- 93. (Previously Presented) The method of claim 89 wherein the planarizing medium includes a polishing pad having conductive particles and applying a signal includes applying a signal that produces an electrostatic attractive force between the platen and the conductive particles.
- 94. (Previously Presented) The method of claim 89 wherein applying a signal includes applying a voltage to the platen.

95-98. (Cancelled)

- 99. (Previously Presented) The method of claim 92, further comprising locking the support member to the platen with a locking device positioned on the support member that is engageably received by the platen.
- 100. (Previously Presented) A method for removably attaching a planarizing medium to a platen of a planarizing machine, comprising:

distributing a plurality of conductive particles in the planarizing medium; and applying a signal to the platen that produces an electromagnetic attractive force between the platen and the conductive particles in the planarizing medium.

- 101. (Previously Presented) The method of claim 100, further comprising positioning the platen adjacent to the planarizing medium.
- 102. (Previously Presented) The method of claim 100 wherein the platen includes a conductive plate positioned within the platen, and applying a signal includes applying a signal to the conductive plate positioned within the platen.
- 103. (Previously Presented) The method of claim 100 wherein distributing a plurality of conductive particles further comprises distributing the plurality of conductive particles uniformly in the planarizing medium.
- 104. (Previously Presented) The method of claim 101 wherein distributing a plurality of conductive particles further comprises concentrating the plurality of conductive particles in a portion of the planarizing medium adjacent to the platen.
- 105. (Previously Presented) The method of claim 100 wherein distributing a plurality of conductive particles further comprises distributing a plurality of particles in the planarizing medium that are comprised of a ferrous material.

- 106. (Previously Presented) The method of claim 100, wherein applying a signal includes applying a current to the platen.
- 107. (Previously Presented) A method for releasably attaching a planarizing medium having a plurality of internally distributed conductive particles to a platen of a planarization machine, comprising:

positioning the planarization medium adjacent to the platen; and coupling a signal to the platen to produce an electromagnetic attractive force between the conductive particles and the platen.

- 108. (Previously Presented) The method of claim 107, wherein the planarizing medium includes an attachment surface having a concentration of conductive particles located proximate to the attachment surface, and positioning the planarizing medium is further comprised of positioning the attachment surface on the platen.
- 109. (Previously Presented) The method of claim 107, wherein the platen includes a conductive member positioned within the platen, and coupling a signal to the platen further comprises coupling a signal to the conductive member.
- 110. (Previously Presented) The method of claim 107, wherein coupling a signal includes coupling a current to the platen.